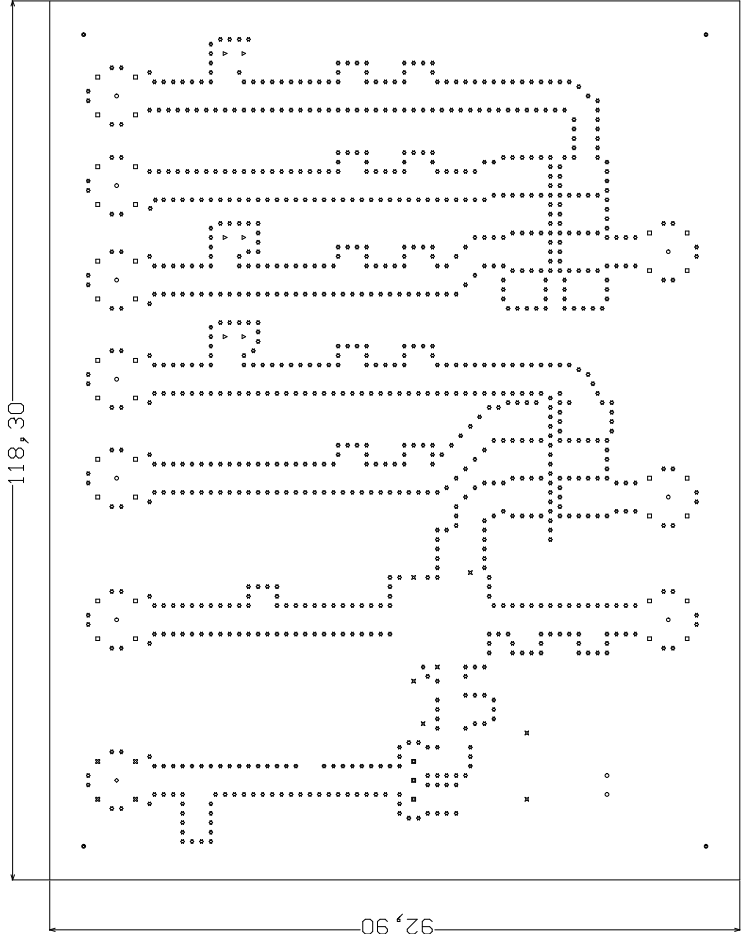


Layer	Name	Material	Thickness	Constant	Board Layer Stack	Board Layer Stack	Board Layer Stack
1	TopOverlay						
2	TopSolder	Solder Resist	0,020mm	4			
3	TopLayer	Copper	0,035mm				
4	Dielectric1	FR-4	1,465mm	4,74			
5	BottomLayer	Copper	0,035mm				
6	BottomSolder	Solder Resist	0,020mm	4			
7	BottomOverlay						



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer	Pair	Uia/Pad	Pad Shape
◇	1	1,500mm (39,06ml)	PTH	Round	TopLayer	BottomLayer	Pad	Rounded
■	3	0,900mm (35,43ml)	PTH	Round	TopLayer	BottomLayer	Pad	Rounded
⊗	4	1,600mm (62,99ml)	PTH	Round	TopLayer	BottomLayer	Pad	Rounded
⊙	4	3,200mm (125,98ml)	PTH	Round	TopLayer	BottomLayer	Uia	Rounded
▽	6	1,000mm (39,37ml)	PTH	Round	TopLayer	BottomLayer	Pad	(Mixed)
⋈	7	0,711mm (28,00ml)	PTH	Round	TopLayer	BottomLayer	Uia	Rounded
○	11	0,711mm (28,00ml)	PTH	Round	TopLayer	BottomLayer	Pad	Rounded
□	36	1,400mm (55,12ml)	PTH	Round	TopLayer	BottomLayer	Pad	Rounded
⊘	962	0,500mm (19,69ml)	PTH	Round	TopLayer	BottomLayer	Uia	Rounded
1034 Total								

MATIERE FR4
CUIVRE (voir empilage)
SERIGRAPHIE BLANCHE FACE
TOP
VERNIS VERT SELECTIF 2 FACES
FINITION NIAU

PISTES 50ohms largeur 1.064mm
face TOP

Radio Oceanography Laboratory				
Indice	Modification		Date	Dessine par
Edition :	CARTE LO-DISTRIB-2021			
Dessinateur : RONVEL	PLAN DE PERCAGE		Folio : 1 / 1	
Date : 09/06/2021			Ind	